## **Product / Process Change Notification**



N° 2019-185-A2

Dear	Customer
Deal	Custoniei

please find attached our INFINEON Technologies PCN:

Final PCN: Several changes affecting Gen 5P Mosfets for D2PAK, DPAK, TO220 packages

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2021-04-12.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates:
   "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."
   Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon Technologies to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

# **Product / Process Change Notification**



### N° 2019-185-A2

Products affected Please refer to attached affected product list 1\_cip19185\_A2



**Detailed Change Information** 

**Subject:** Final PCN: Several changes affecting Gen 5P Mosfets for D2PAK, DPAK, TO220

packages

Reason / Motivation: Production consolidation

Description	<u>Old</u>	New
PROCESS - WAFER PRODUCTION: New / change of metallization (specifically chip backside)		Ti/Ni/Ag Evaporation Process
PROCESS - WAFER PRODUCTION: New / change of metallization (specifically chip frontside)	Al/Si	Al/Si/Cu
PROCESS - WAFER PRODUCTION: Move of all or part of wafer fab to a different location/site/subcontractor	Infineon Technologies Americas Corp., Temecula, United States	EPISIL Technologies Inc., Taiwan
PROCESS - ASSEMBLY: Change in leadframe dimensions	Dpak part AUIRFR5410TRL only: Single gage leadframe	Dpak part AUIRFR5410TRL only: Dual gage leadframe
PROCESS - ASSEMBLY: Change of lead frame finishing material / area (internal)	•	TFME Only TO220 and Dpak: Bare Cu in all area
PROCESS - ASSEMBLY: Die attach material	Dpak parts 94-4103PBF, 94- 4918PBFonly: Die Attach material 44- 0014	Dpak parts 94-4103PBF, 94-4918PBF only: Die attach material 44-0314
	Dpak parts AUIRFR5305, AUIRFR5305TR, AUIRFR5305TRL only: 12 mil Al bond wire	Dpak parts , AUIRFR5305, AUIRFR5305TR, AUIRFR5305TRL only: 10 mil Al bond wire
PROCESS - ASSEMBLY: Change of mold compound / encapsulation material	TO220 only: MG15F-35A	TFME only TO220 only: KE-G300BH
PROCESS - ASSEMBLY: Change of product marking	TO220 and Dpak: No Site code	TFME affected only: TO220 and Dpak; Site Code M
	TO220 and Dpak: Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico	TO220 and Dpak: Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico and Tongfu Microelectronics Co., Ltd(TFME)

## **Product / Process Change Notification**



#### N° 2019-185-A2

TEST FLOW: Americas Corp., Temecula, United

Move of all or part of electrical States

wafer test and/or final test to a TO220 and Dpak: Final Test

different location/site/subcontractor Rectificadores Internacionales, S.A. de

C.V., Tijuana , Mexico

Wafer Probe site: Infineon Technologies Wafer Probe site: EPISIL Technologies

Inc., Taiwan

TO220 and Dpak: Final Test,

Rectificadores Internacionales, S.A. de

C.V., Tijuana, Mexico and Tongfu Microelectronics Co., Ltd(TFME)

**Product Identification** 

Traceability assured via Lot number an date code.

**Anticipated Impact of Change** 

No expected impact on electrical performance. Quality and reliability verified by

qualification.

DeQuMa-ID(s): SEM-PW-06 / SEM-PW-07 / SEM-PW-13 / SEM-PA-03 / SEM-PA-

04 / SEM-PA-07 / SEM-PA-08 / SEM-PA-11 / SEM-PA-13 / SEM-PA-18 / SEM-TF-01

**Attachments** 

1\_cip19185\_A2 affected product list

3\_cip19185\_A2 customer information package

## **Time Schedule**

Final qualification report	2021-02-28
First samples available	2021-02-28
Intended start of delivery [1]	2021-10-31
Last Order Date (LOD) [2]	2021-04-30
Last Delivery Date (LDD) [3]	2021-10-31

<sup>[1]</sup> Provided date or earlier after customer approval

If you have any questions, please do not hesitate to contact your local Sales Office.

<sup>[2]</sup> Last time buy volume to be placed latest until LOD

<sup>[3]</sup> Delivery of new product can be earlier (see Intended start of delivery) and depends on approval